

FIG. 2A
(Prior Art)

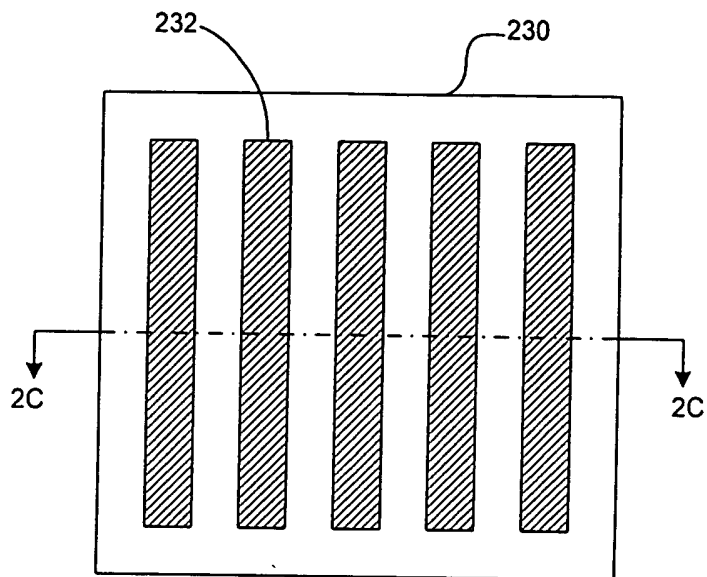


FIG. 2B
(Prior Art)

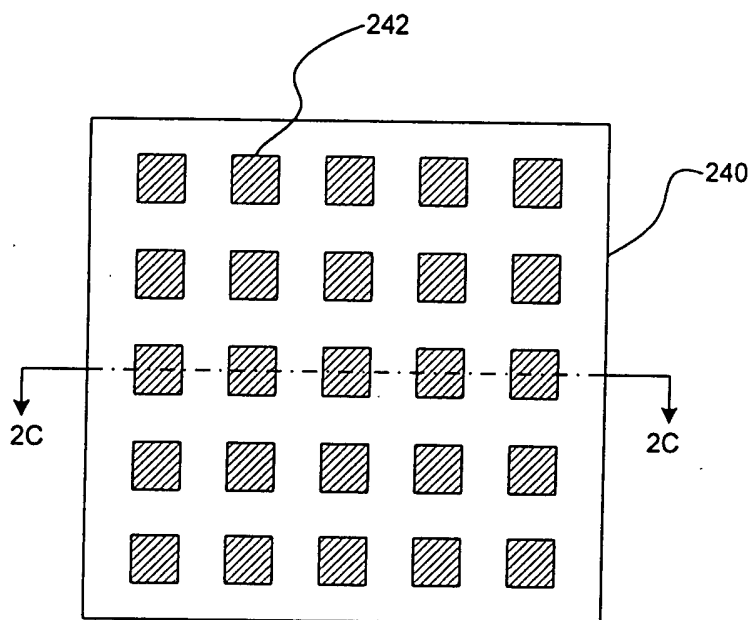


FIG. 2C
(Prior Art)

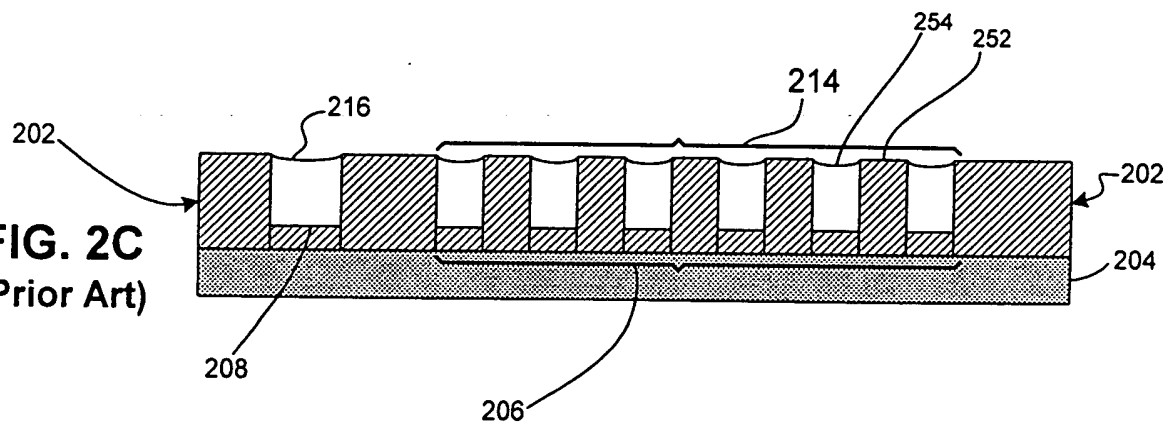


FIG. 3A

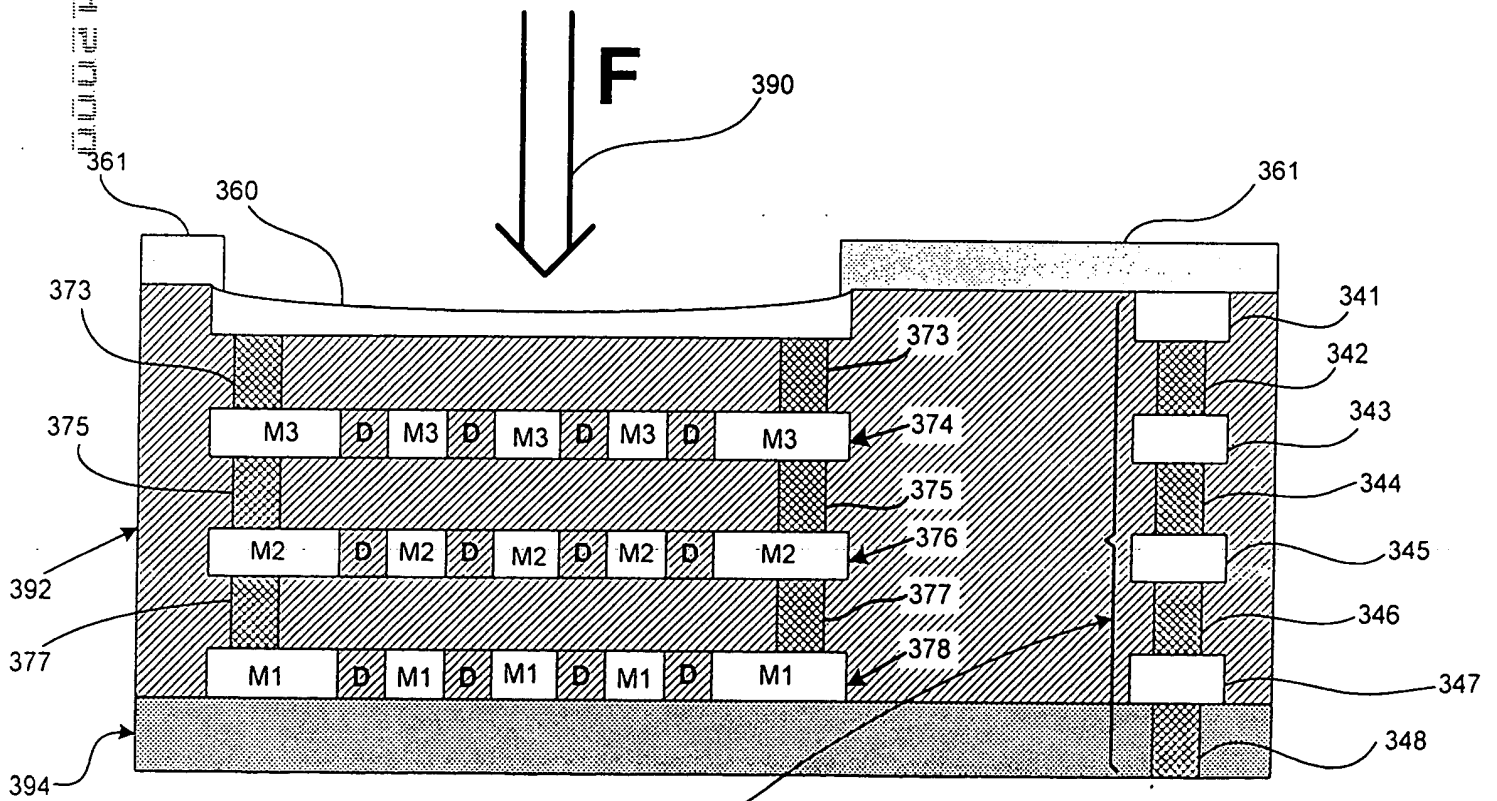
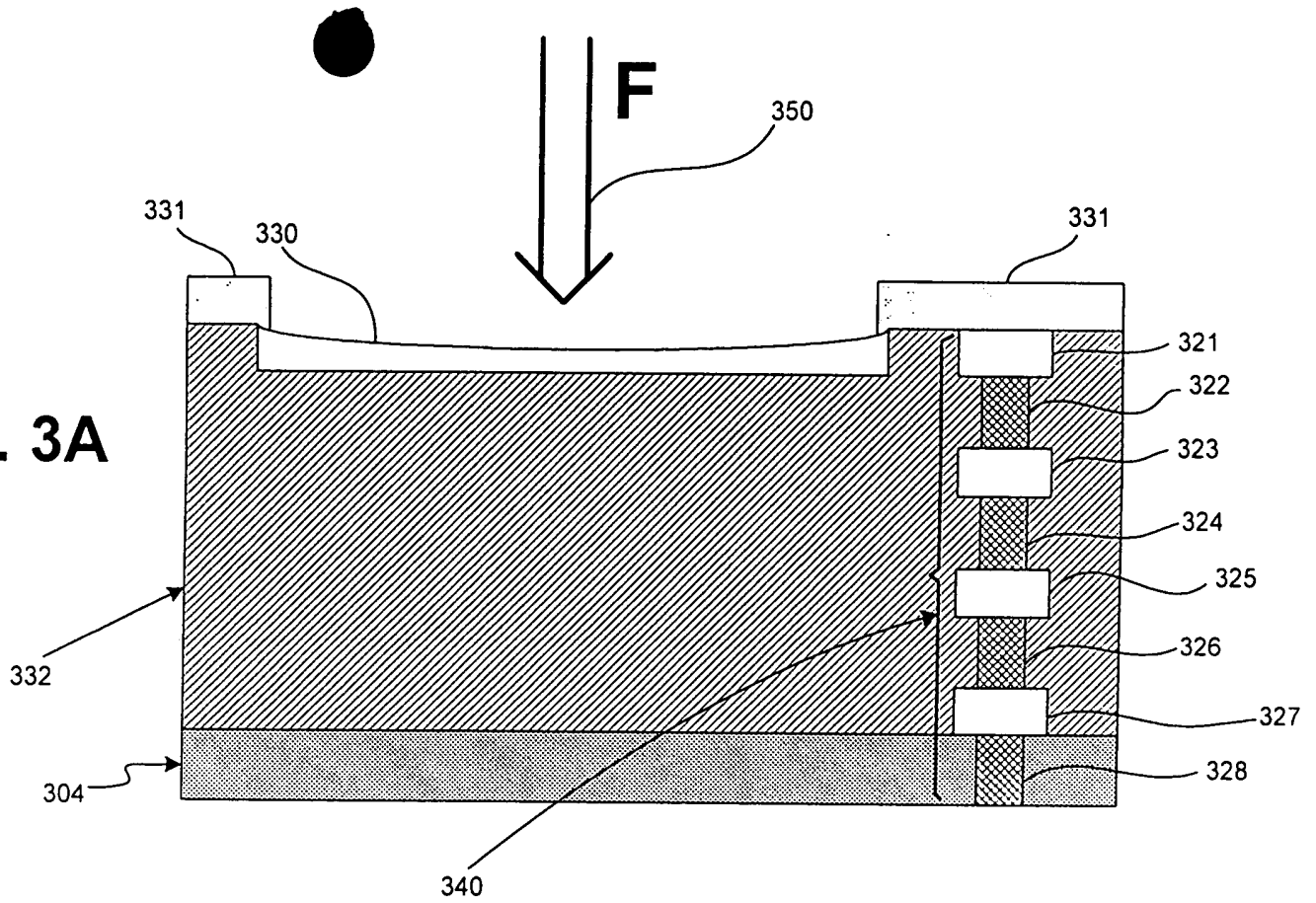
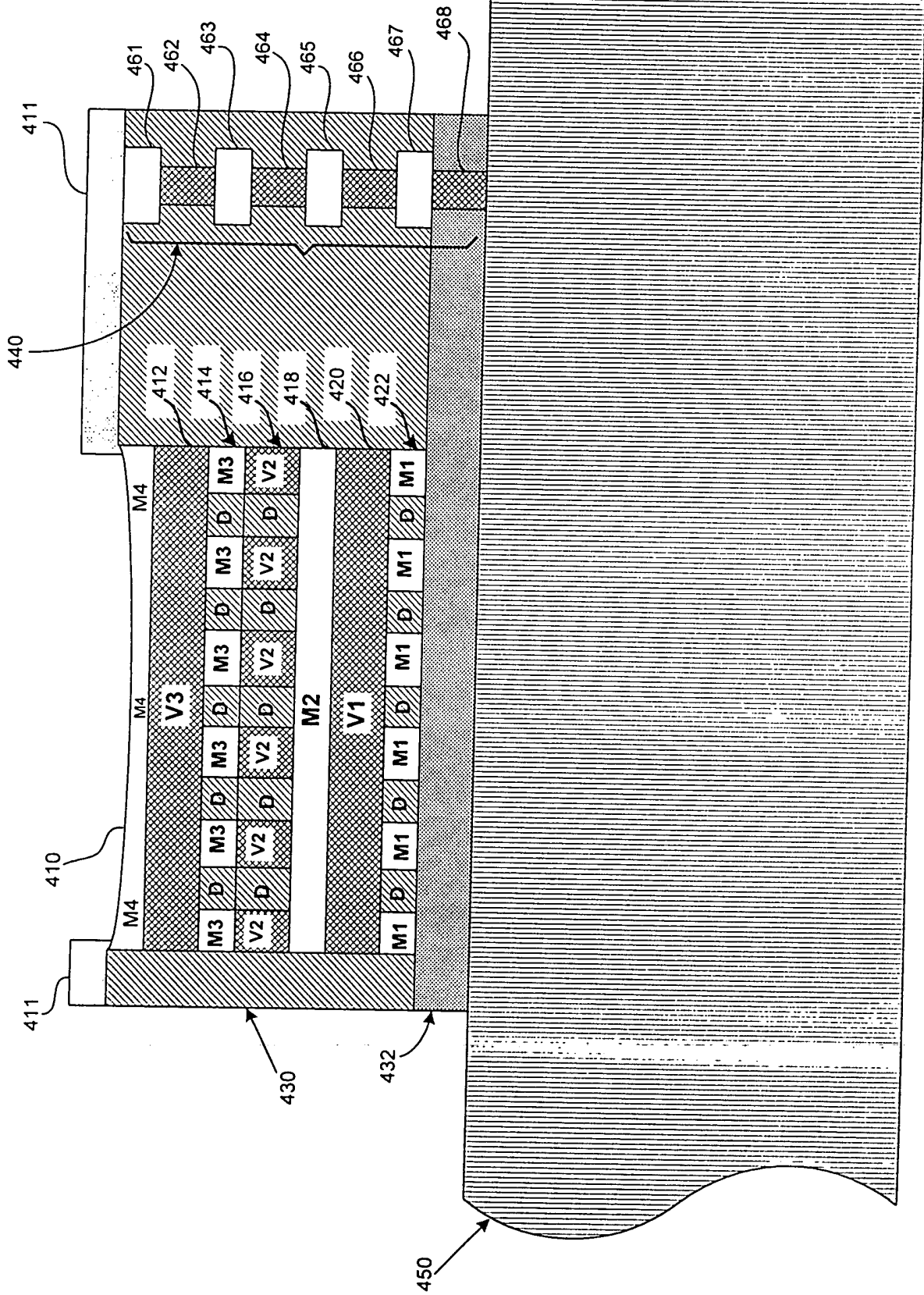


FIG. 3B

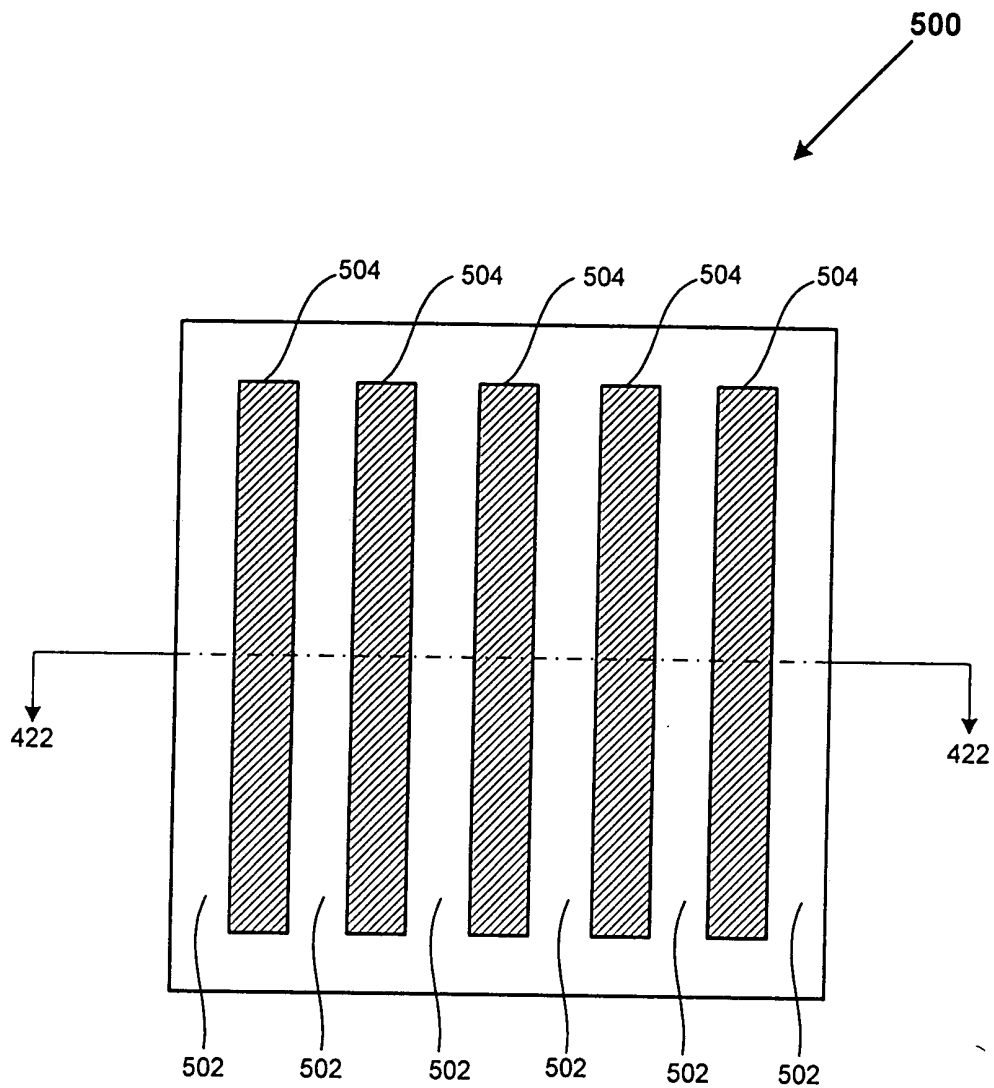
FIG. 4

FIG. 4 is a cross-sectional view of a device 400.

400

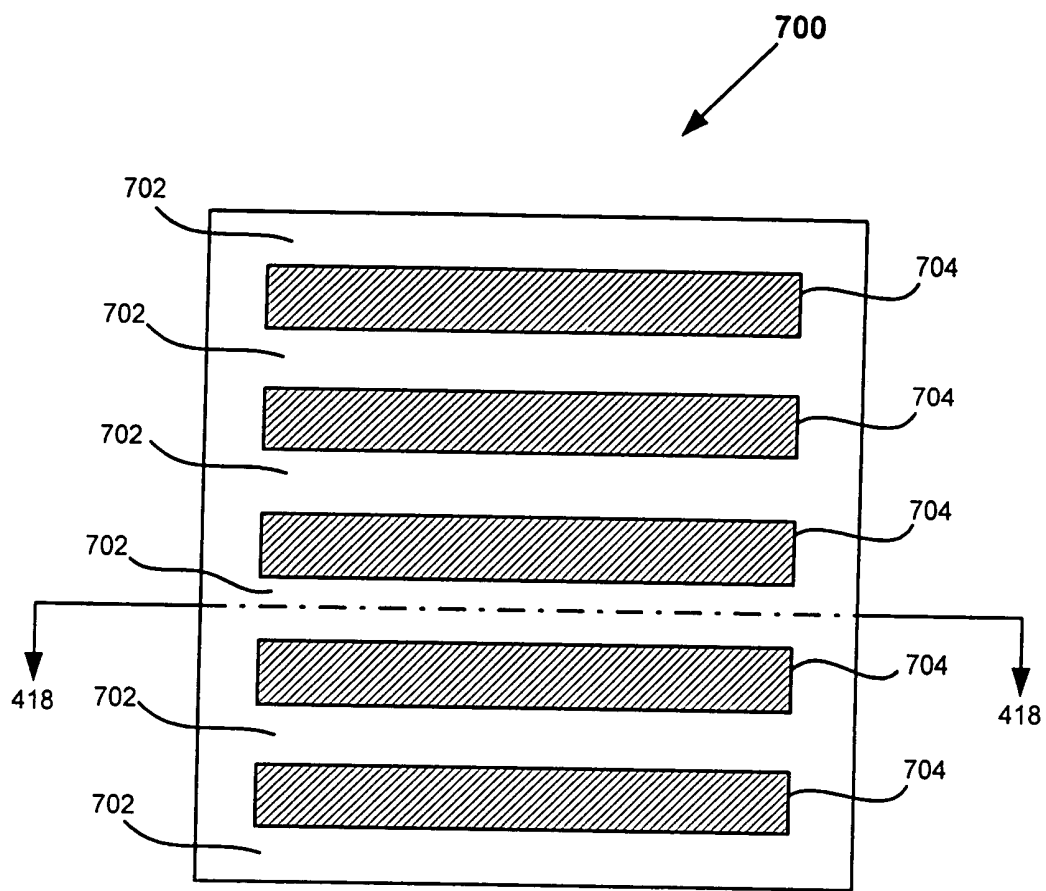


0000050960



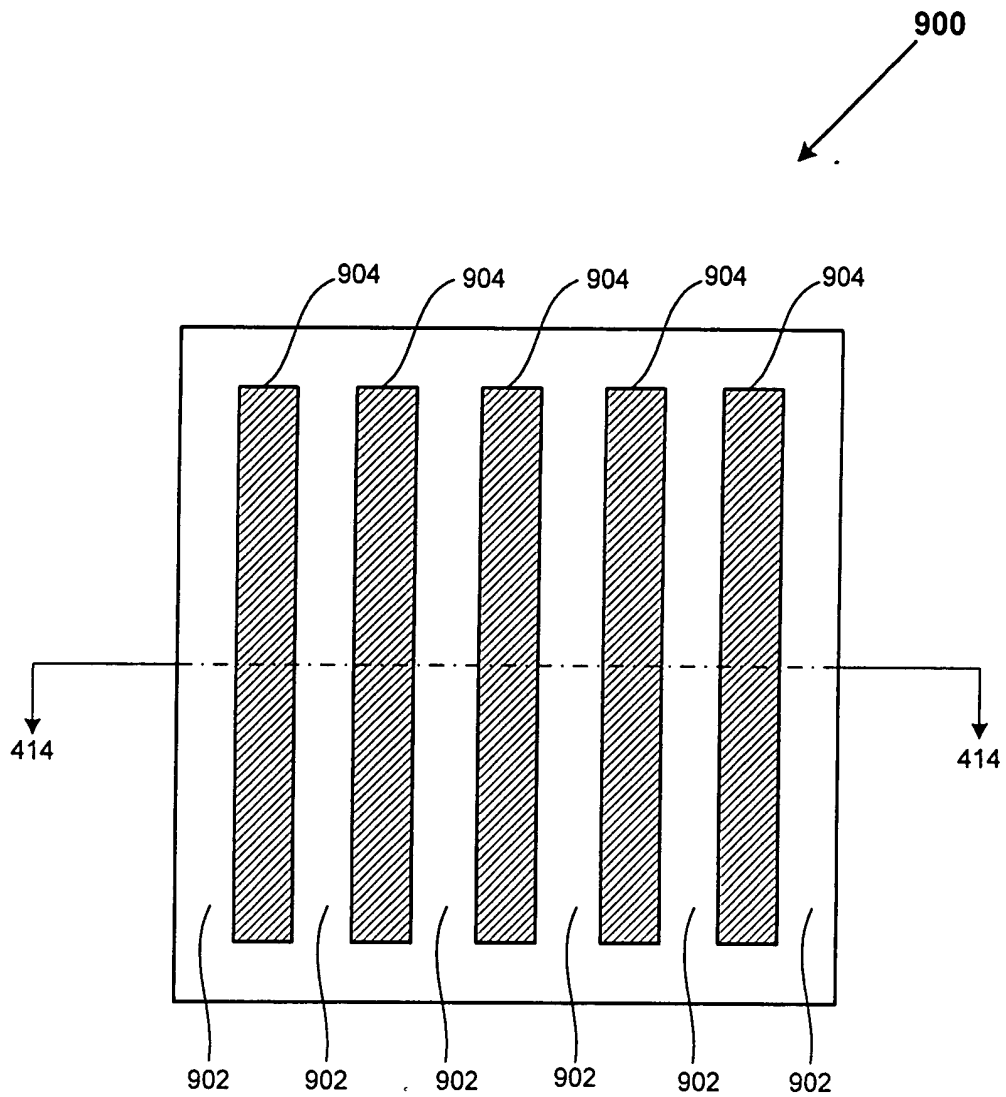
Top View of Metal Pad Structure 422 in Figure 4

FIG. 5

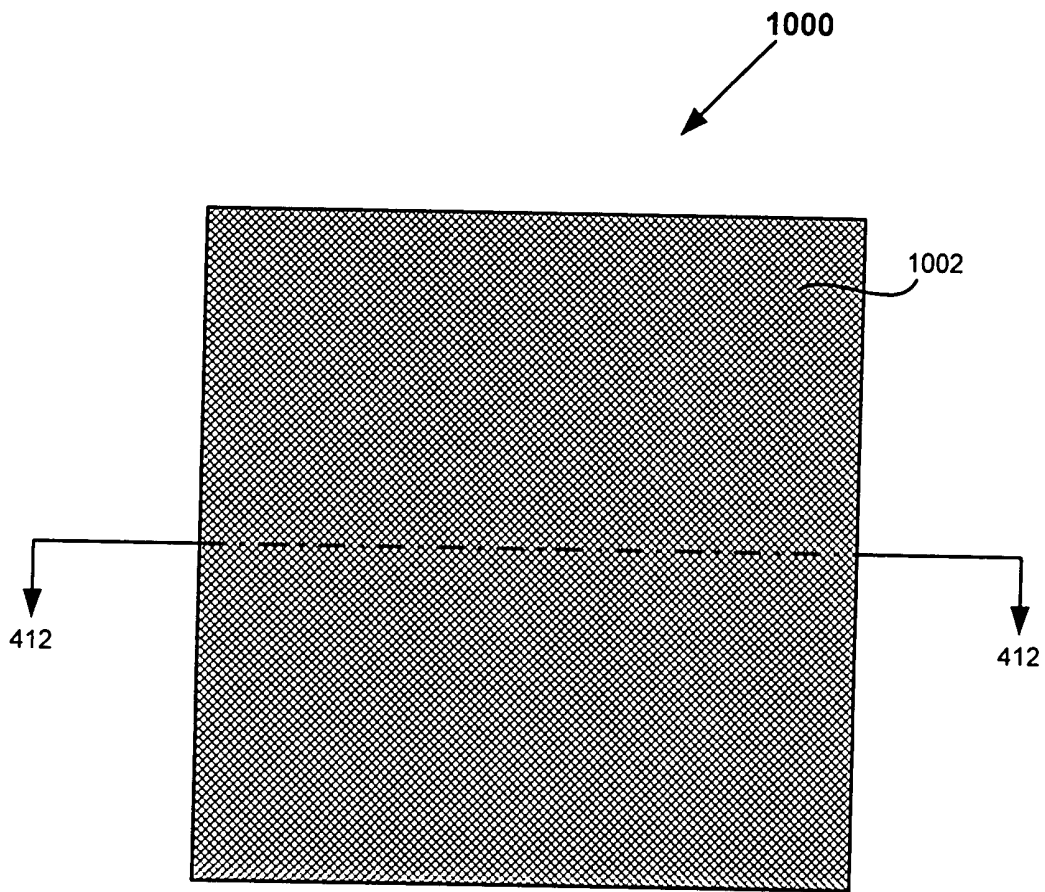


Top View of Metal Pad Structure 418 in Figure 4

FIG. 7

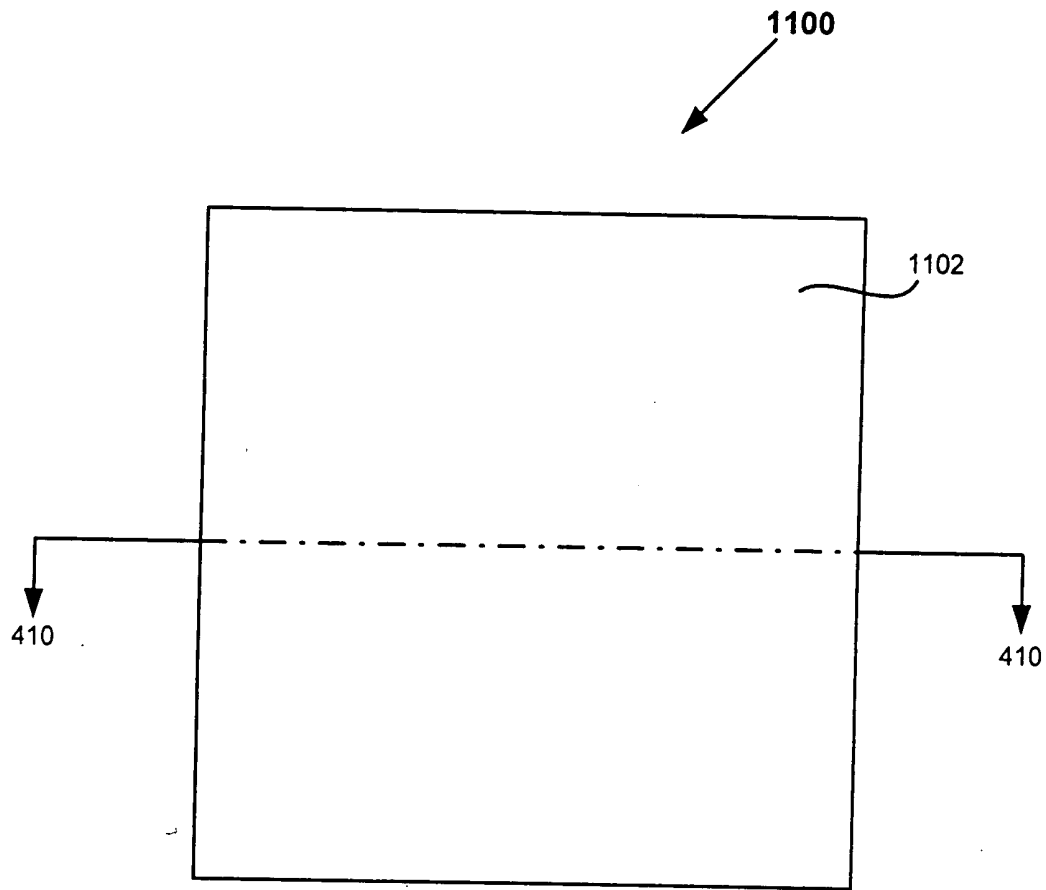


Top View of Metal Pad Structure 414 in Figure 4



Top View of Via Pad Structure 412 in Figure 4

FIG. 10



Top View of Bonding Pad 410 in Figure 4

FIG. 11

1200

1202

1202

1204

1206

1208

1202

1202



Columns having only interconnect metal and via metal



Columns having dielectric only



Columns having interconnect metal, via metal, and dielectric

FIG. 12